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 TI Cladding materials for sputtering targets
 IN Ishikura, Chiharu
 PA Tanaka Noble Metal Industrial Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 3 pp.
 CODEN: JKXXAF
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 LA Japanese
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 01096374	A	19890414	JP 1987-251174	19871005
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AB	The material is made of Cu >99.7%, and Zn, In, Mn, Sb, Be, Ca, Cr, Te, Y, Nb, Mo, Ta, and/or Sn 100-3000 ppm for separation of the backing plate in exchange of the target and efficient cooling.				